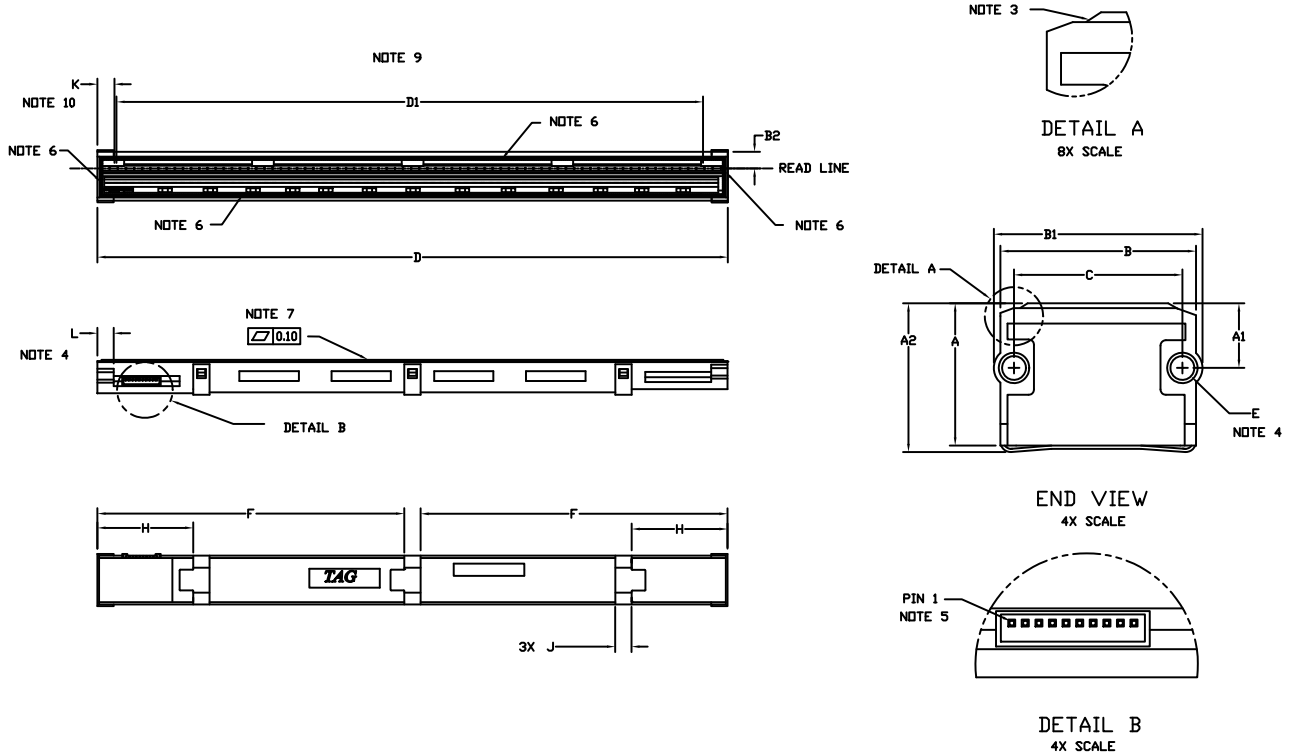


**IMAGE SENSOR MODULE  
CASE MODAC  
ISSUE A**

DATE 11 MAY 2010



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEADING EDGE OF THE APPROACH ANGLE ON THE GLASS IS LOWER THAN THE TOP OF THE HOUSING.
4. BORE DEPTH IS 6.0 WITH A 0.3 LEAD-IN CHAMFER.
5. PIN HEADER, MODEL NUMBER EBW-PK23-P010L2-3Z, 1X10 PIN, PITCH 1.25.
6. GLASS IS GLUED ON ALL 4 SIDES.
7. GLASS THICKNESS IS 1.85.
8. USE M2.3 SELF TAPPING SCREWS FOR MOUNTING. TORQUE SCREWS BETWEEN 1.80 KGF-CM AND 2.00 KGF-CM.
9. DIMENSION D1 DENOTES THE SCAN LENGTH.
10. DIMENSION K DENOTES THE POSITION OF THE FIRST PIXEL.

DIM	MILLIMETERS	
	MIN	MAX
A	12.60	13.60
A1	5.45	6.45
A2	13.20	14.20
B	17.70	18.30
B1	18.90	19.50
B2	5.50	6.50
C	15.40	15.60
D	231.60	232.60
D1	216.00	REF
E	2.10	2.30
F	112.50	113.50
H	34.80	35.80
J	5.70	6.30
K	5.30	7.30
L	6.00	REF

<b>DOCUMENT NUMBER:</b>	<b>98AON48436E</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>IMAGE SENSOR MODULE</b>	<b>PAGE 1 OF 1</b>

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.